SN74HCT244-EP
OCTAL BUFFER AND LINE DRIVER WITH 3-STATE OUTPUTS

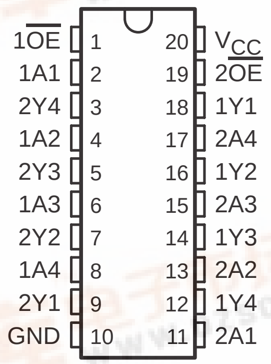
SCLS562 − JANUARY 2004

- **Controlled Baseline**
  - **One Assembly/Test Site, One Fabrication Site**
- **Extended Temperature Performance of −40°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree**[†]
- **Operating Voltage Range of 4.5 V to 5.5 V**
- **High-Current Outputs Drive Up To 15 LSTTL Loads**
- **Low Power Consumption, 160-μA Max I_{CC}**

[†] Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- **Typical t_{pd} = 13 ns**
- **±6-mA Output Drive at 5 V**
- **Low Input Current of 1 μA Max**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines or Buffer Memory Address Registers**

PW PACKAGE
(TOP VIEW)



description/ordering information

This octal buffer and line driver is designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The SN74HCT244 device is organized as two 4-bit buffers/drivers, with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the device passes noninverted data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

ORDERING INFORMATION

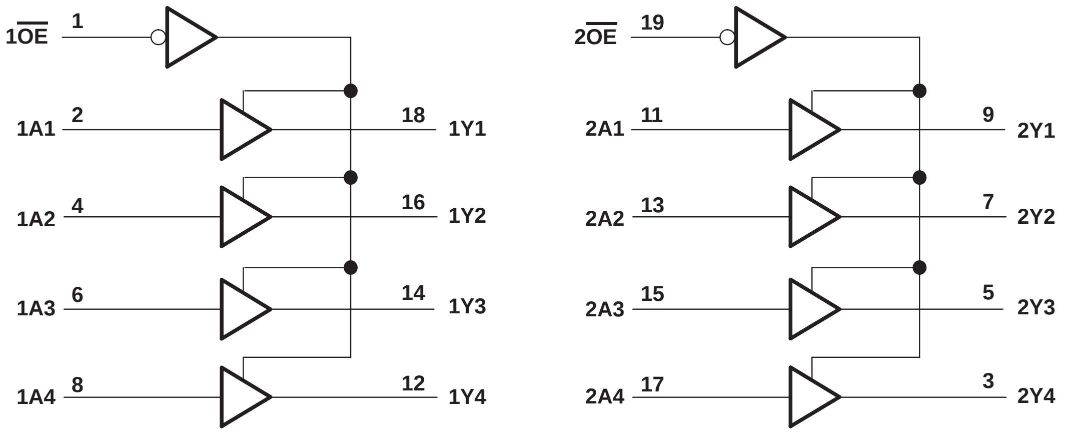
T_A	PACKAGE[‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 125°C	TSSOP − PW	Tape and reel	SN74HCT244QPWREP	SHT244EP

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each buffer/driver)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V_{CC} or GND	±70 mA
Package thermal impedance, θ_{JA} (see Note 2)	83°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 4.5 V to 5.5 V	2			V
V_{IL}	Low-level input voltage	V_{CC} = 4.5 V to 5.5 V			0.8	V
V_I	Input voltage		0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	V
$\Delta t/\Delta v$	Input transition rise/fall time				500	ns
T_A	Operating free-air temperature		−40		125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C MIN	T_A = 25°C TYP	T_A = 25°C MAX	MIN	MAX	UNIT
V_{OH}	$V_I = V_{IH}$ or V_{IL}	I_{OH} = −20 µA	4.5 V	4.4	4.499		4.4		V
		I_{OH} = −6 mA		3.98	4.3		3.7		
V_{OL}	$V_I = V_{IH}$ or V_{IL}	I_{OL} = 20 µA	4.5 V		0.001	0.1		0.1	V
		I_{OL} = 6 mA			0.17	0.26		0.4	
I_I	$V_I = V_{CC}$ or 0		5.5 V		±0.1	±100		±1000	nA
I_{OZ}	$V_O = V_{CC}$ or 0,	$V_I = V_{IH}$ or V_{IL}	5.5 V		±0.01	±0.5		±10	µA
I_{CC}	$V_I = V_{CC}$ or 0,	I_O = 0	5.5 V			8		160	µA
ΔI_{CC}†	One input at 0.5 V or 2.4 V, Other inputs at 0 or V_{CC}		5.5 V		1.4	2.4		3	mA
C_i			4.5 V to 5.5 V		3	10		10	pF

† This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C MIN	T_A = 25°C TYP	T_A = 25°C MAX	MIN	MAX	UNIT
t_{pd}	A	Y	4.5 V		15	28		42	ns
			5.5 V		13	25		38	
t_{en}	$\overline{OE}$	Y	4.5 V		21	35		53	ns
			5.5 V		19	32		48	
t_{dis}	$\overline{OE}$	Y	4.5 V		19	35		53	ns
			5.5 V		18	32		48	
t_t		Y	4.5 V		8	12		18	ns
			5.5 V		7	11		16	

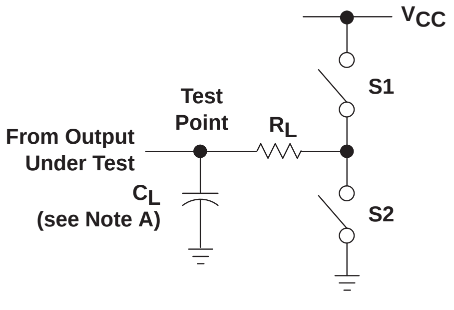
switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C MIN	T_A = 25°C TYP	T_A = 25°C MAX	MIN	MAX	UNIT
t_{pd}	A	Y	4.5 V		21	45		68	ns
			5.5 V		18	40		61	
t_{en}	$\overline{OE}$	Y	4.5 V		25	52		79	ns
			5.5 V		22	47		71	
t_t		Y	4.5 V		17	42		63	ns
			5.5 V		14	38		57	

operating characteristics, T_A = 25°C

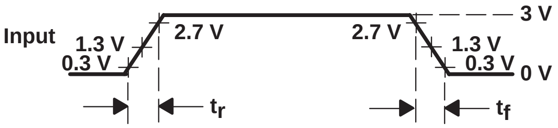
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer/driver	No load	40	pF

PARAMETER MEASUREMENT INFORMATION

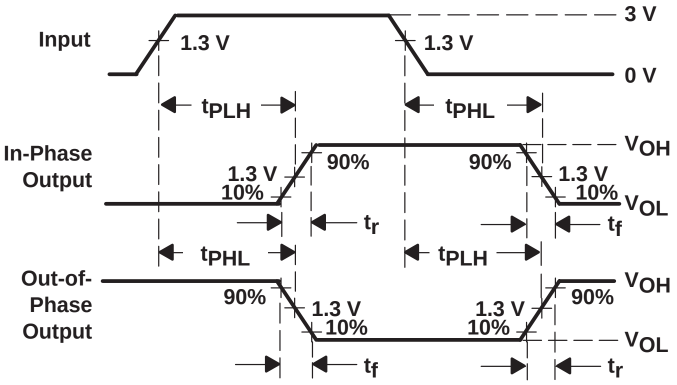


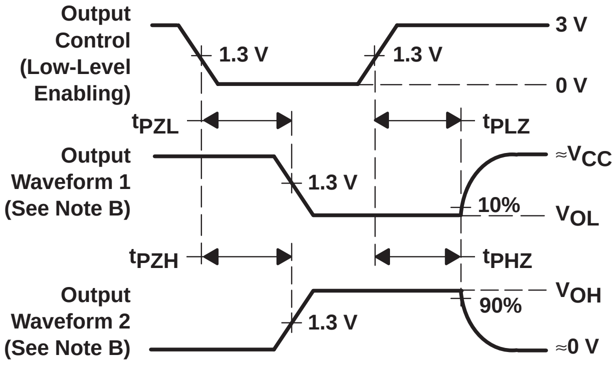
LOAD CIRCUIT

PARAMETER		R_L	C_L	S1	S2
t_{en}	t_{PZH}	1 kΩ	50 pF or 150 pF	Open	Closed
	t_{PZL}			Closed	Open
t_{dis}	t_{PHZ}	1 kΩ	50 pF	Open	Closed
	t_{PLZ}			Closed	Open
t_{pd} or t_t		––	50 pF or 150 pF	Open	Open



VOLTAGE WAVEFORM
INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT RISE AND FALL TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES:
A. C_L includes probe and test-fixture capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 6 ns, t_f = 6 ns.
D. The outputs are measured one at a time with one input transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74HCT244QPWREP	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04698-01XE	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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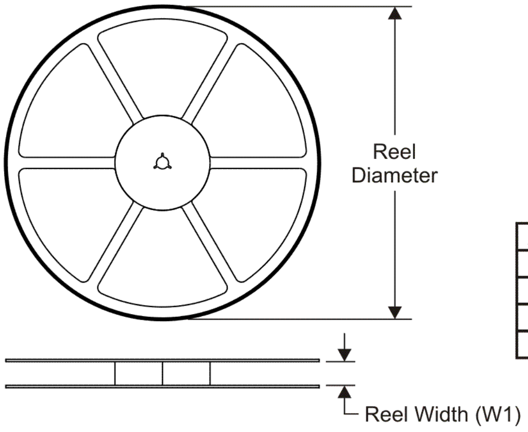
OTHER QUALIFIED VERSIONS OF SN74HCT244-EP :
- Catalog: SN74HCT244
- Automotive: SN74HCT244-Q1
- Military: SN54HCT244

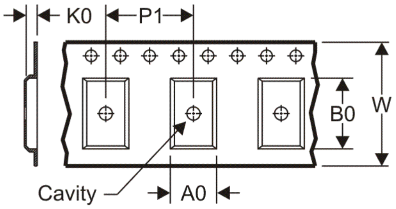
NOTE: Qualified Version Definitions:
  - Catalog - TI's standard catalog product
  - Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
  - Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

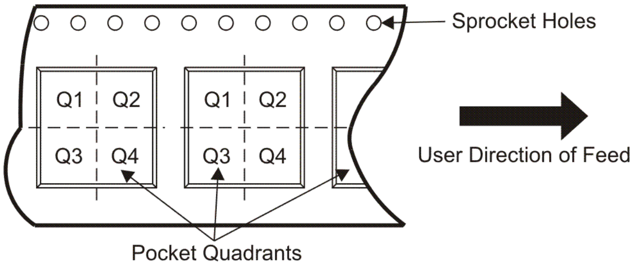


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

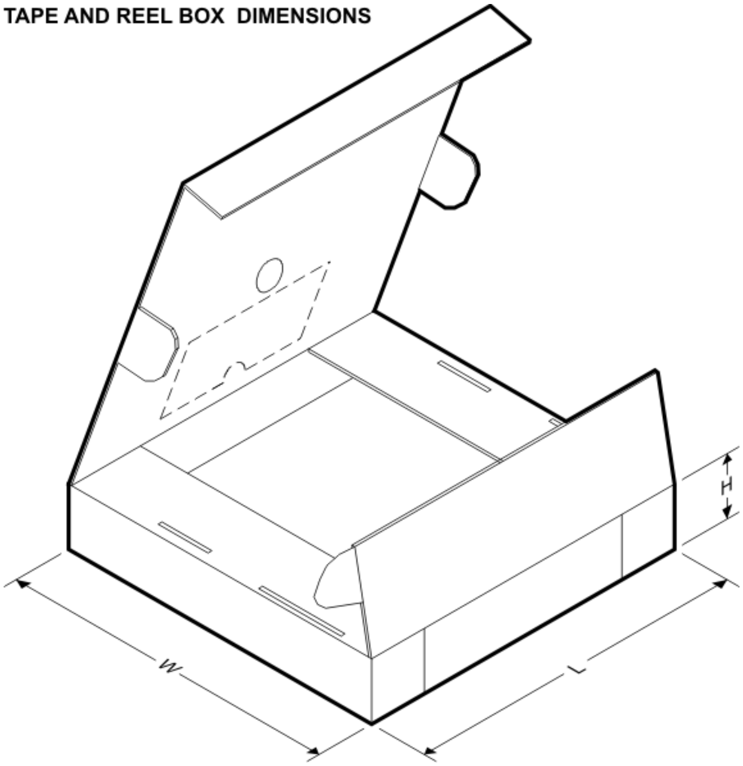
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT244QPWREP	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

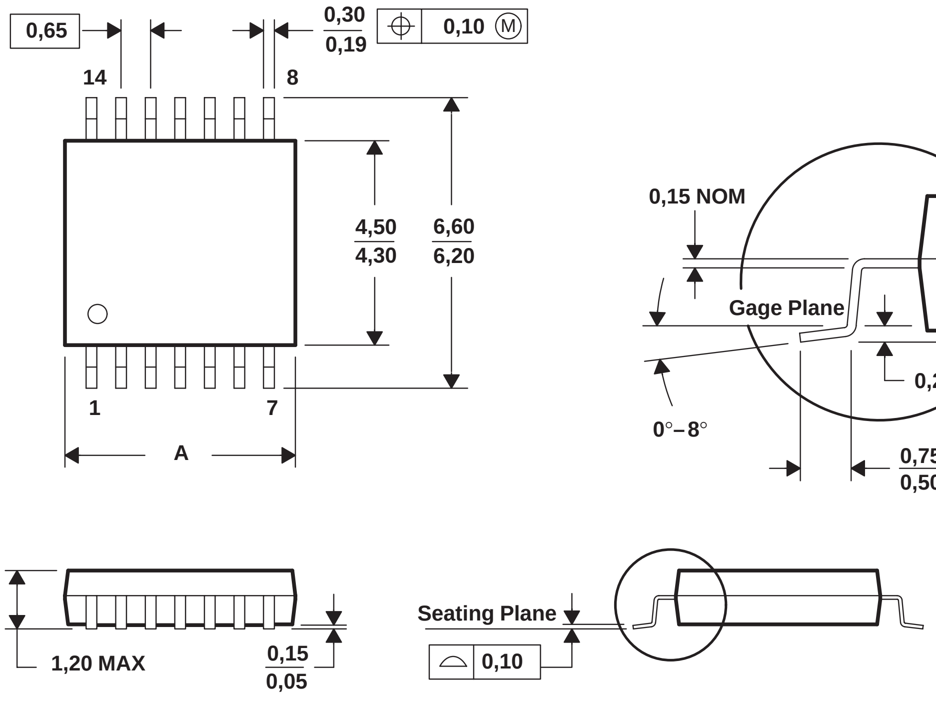


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCT244QPWREP	TSSOP	PW	20	2000	346.0	346.0	33.0

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



PINS ** / DIM	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

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NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153

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